

SEP 20 2004

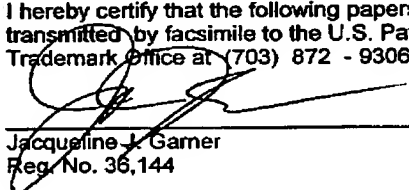
**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

Applicant:	Mena et al.	Art Unit:	2823
Serial No.:	09/895,524	Examiner:	Fourson III
Filing Date:	06/28/2001	Docket No.:	TI-29612
Customer No.:	23494	Conf. No.:	8193

Title: HDP LINER LAYER PRIOR TO HSQ/SOG DEPOSITION TO REDUCE THE AMOUNT OF HSQ/SOG OVER THE METAL LEAD

**REQUEST FOR RECONSIDERATION AFTER FINAL**

Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

<p align="center"><b>CERTIFICATION OF FACSIMILE TRANSMISSION</b></p> <p>I hereby certify that the following papers are being transmitted by facsimile to the U.S. Patent and Trademark Office at (703) 872 - 9306 on 9/20/2004.</p>  <p>_____ Jacqueline J. Garner Reg. No. 36,144</p>
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Dear Sir:

The following remarks are offered in response to the Examiner's Office Action dated 05/19/2004. They are respectfully submitted as a full and complete response to that Action.

Reconsideration of the above-referenced application in view of the following remarks is respectfully requested.

Claims 1-12 are pending in this case.

The Examiner rejected claims 1, 3, 5 and 12 under 35 U.S.C. § 103(a) as being unpatentable over AAPA in combination with Ngo et al. and Yao et al.

Applicant respectfully submits that claim 1 is patentable over the AAPA in view of Ngo and Yao as there is no disclosure or suggestion in the references of forming both a HDP liner layer, wherein a portion of the HDP liner layer over metal leads has

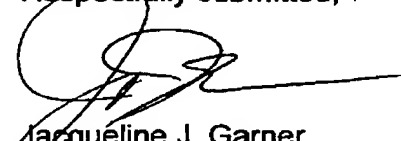
Appl. No. 09/895,524  
Reply to Office action of 05/19/2004

sloped edges and a gap-fill layer over the liner layer. The AAPA teaches both a liner layer and a gap fill layer, but does not teach the liner layer being a HDP liner layer with a portion over the metal leads having sloped edges. Ngo and Yao teach HDP gap fill layers, but not HDP liner layers. At most, Ngo and Yao would suggest replacing the gap fill layer of the AAPA with an HDP layer or replacing both the liner and gap fill layer of the AAPA with a single HDP gap fill layer. There is no suggestion provided by the prior art for replacing the liner layer of the AAPA with an HDP liner layer where a portion of the HDP liner layer over metal leads has sloped edges while retaining a gap fill layer as claimed. The fact that Ngo teaches a gap filling HDP layer as a first layer over the metal does not provide a suggestion for modifying the gap fill HDP layer of Ngo and using it to replace only a liner layer of the AAPA to accomplish the claimed invention. Accordingly, Applicant respectfully submits that claim 1 and the claims dependent thereon are patentable over the AAPA in view of Ngo and Yao.

Applicant notes that only a rejection of claims 1, 3, 5, and 12 is made in the latest Office Action. Have the remaining claims been allowed?

In light of the above, Applicant respectfully requests withdrawal of the Examiner's rejections and allowance of claims 1-12. If the Examiner has any questions or other correspondence regarding this application, Applicant requests that the Examiner contact Applicant's attorney at the below listed telephone number and address.

Respectfully submitted,



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